


RoHS COMPLIANT

- △1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material;
Non-clad
- △2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- △3 Solder Balls: Sn96.5Ag3.0Cu0.5

Description: Giga-snaP BGA SMT Foot
449 position terminal pins (0.8mm centers, 25x25 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	SF-BGA449A-B-61F Drawing	Status: Released	Scale: 4:1	Rev: B
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